

#### **Product Summary**

Device	BV <sub>DSS</sub>	Rds(on) Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C	
Q1	20V	0.5Ω @ V <sub>GS</sub> = 4.5V	1030mA	
QI		200	200	0.9Ω @ V <sub>GS</sub> = 1.8V
Q2	-20V	1.0Ω @ Vgs = -4.5V	-700mA	
QZ	-200	2.0Ω @ V <sub>GS</sub> = -1.8V	-460mA	

#### Description

This new generation MOSFET has been designed to minimize the on-state resistance ( $R_{DS(ON)}$ ) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

#### **Applications**

- Power Management Functions
- Battery Operated Systems and Solid-State Relays
- Load Switch

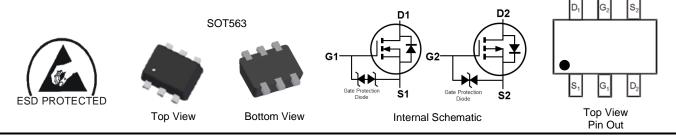
#### **Features and Benefits**

- Low On-Resistance
  - Low Gate Threshold Voltage  $V_{GS(TH)}$  <1V
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Complementary Pair MOSFET
- Ultra-Small Surface Mount Package
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative.

https://www.diodes.com/quality/product-definitions/

#### **Mechanical Data**

- Case: SOT563
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
   Woight: 0.002 grame (Approximate)
- Weight: 0.003 grams (Approximate)



# Ordering Information (Note 4)

563 3000/Tape & Reel						
563 8000/Tape & Reel (Note 5)						
DMC2400UV-13 SOT563 10000/Tape & Reel						

No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</p>

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

5. Change the pitch from 4mm to 2mm in T&R.

### **Marking Information**

Date Code Key			 	A3 YM	YN	/I = Date C = Year (ex:	ict Type Ma ode Markin : H = 2020 ex: 9 = Sep	) Č	e			
Year	2011		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	Y		Н	I	J	K	L	М	N	0	Р	R
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# Maximum Ratings - Q1 N-CHANNEL (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage			V <sub>DSS</sub>	20	V
Gate-Source Voltage			V <sub>GSS</sub>	±12	V
	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	1030 800	mA
Continuous Drain Current (Note 7) $V_{GS} = 4.5V$	t<10s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	1150 900	mA
	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	lо	740 570	mA
Continuous Drain Current (Note 7) $V_{GS} = 1.8V$	t<10s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	870 700	mA
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			IDM	3	А
Maximum Body Diode Continuous Current			ls	800	mA

# Maximum Ratings - Q2 P-CHANNEL (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	-20	V		
Gate-Source Voltage			Vgss	±8	V
Steady $T_A = +25^{\circ}C$ State $T_A = +70^{\circ}C$		ID	-700 -550	mA	
Continuous Drain Current (Note 7) $V_{GS} = -4.5V$	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ID	-820 -640	mA
Steady $T_A = +25^{\circ}C$ State $T_A = +70^{\circ}C$			ID	-460 -350	mA
Continuous Drain Current (Note 7) $V_{GS} = -1.8V$	t<10s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	-550 -420	mA
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			IDM	-2	A
Maximum Body Diode Continuous Current			ls	-800	mA

#### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)		PD	0.45	W
Thermal Desigtance, Junction to Ambient (Nate 6)	Steady State	Davis	281	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	Reja	210	°C/W
Total Power Dissipation (Note 7)		PD	1	W
Thermal Desistance, Junction to Ambient (Note 7)	Steady State	Devi	129	°C/W
Thermal Resistance, Junction to Ambient (Note 7)		Reja	97	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

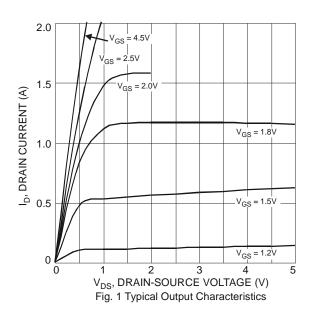
 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. Notes:

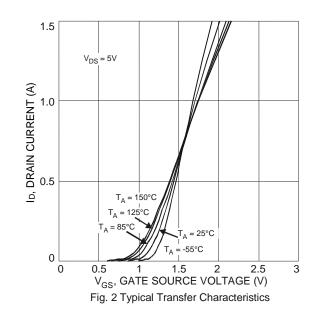


# Electrical Characteristics - Q1 N-CHANNEL (@T<sub>A</sub> = +25°C, unless otherwise specified.)

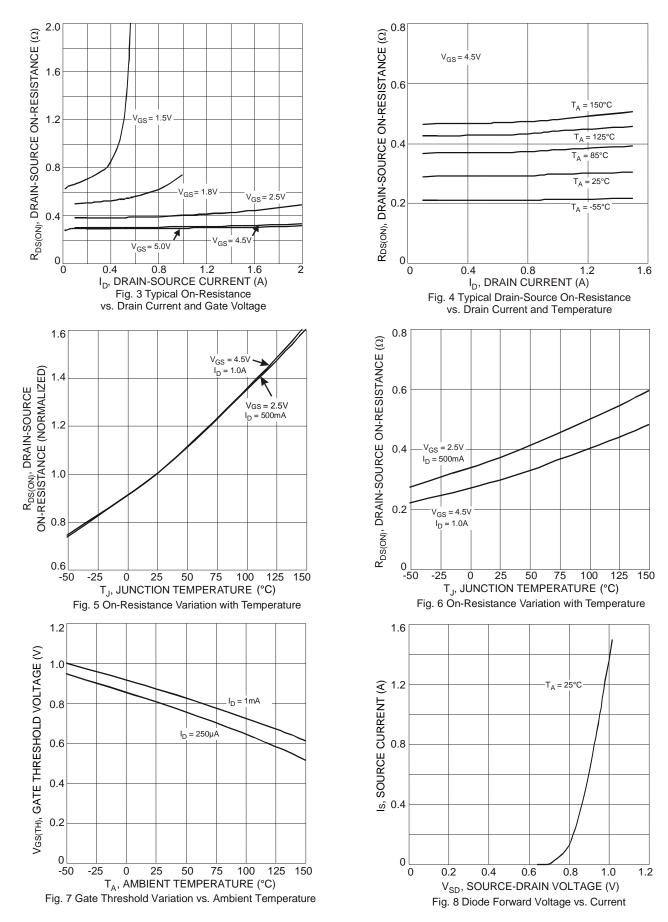
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)					•	
Drain-Source Breakdown Voltage	BVDSS	20	-	_	V	$V_{GS} = 0V, I_D = 1mA$
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	IDSS	_	-	100	nA	$V_{DS} = 20V, V_{GS} = 0V$
		_		±1		$V_{GS} = \pm 5V, V_{DS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	_		±4.0	μA	$V_{GS} = \pm 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	Vgs(th)	0.5	_	0.9	V	VDS = VGS, ID = 250µA
		_	0.3	0.48		$V_{GS} = 5.0V, I_D = 200mA$
		_	0.35	0.5	]	$V_{GS} = 4.5V, I_D = 200mA$
Static Drain-Source On-Resistance	Dear	_	0.45	0.7	Ω	$V_{GS} = 2.5V, I_D = 200mA$
tatic Drain-Source On-Resistance	Rds(on)	_	0.55	0.9	12	$V_{GS} = 1.8V, I_D = 100mA$
		_	0.65	1.5		$V_{GS} = 1.5V, I_D = 50mA$
		_	2	_		Vgs = 1.2V, ID = 1mA
Forward Transfer Admittance	Y <sub>fs</sub>	_	1.4	_	S	V <sub>DS</sub> = 3V, I <sub>D</sub> = 200mA
Diode Forward Voltage	Vsd	_	0.7	1.2	V	Vgs = 0V, Is = 500mA
DYNAMIC CHARACTERISTICS (Note 9)			•	•	•	
Input Capacitance	Ciss	_	37.1	_		
Output Capacitance	Coss	_	6.5	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	4.8	—	1	
Gate Resistance	Rg	_	68	—	Ω	$V_{DS} = 0V, V_{GS} = 0V$
Total Gate Charge	Qg	_	0.5	—		
Gate-Source Charge	Qgs	_	0.07	—	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$ ID = 250mA
Gate-Drain Charge	Q <sub>gd</sub>	_	0.1	—	1	
Turn-On Delay Time	tD(ON)	_	4.06	—		
Turn-On Rise Time	tR	_	7.28	—	nc	$V_{DD} = 10V, V_{GS} = 4.5V,$ $R_L = 47\Omega, R_G = 10\Omega,$
Turn-Off Delay Time	tD(OFF)	_	13.74	_	ns	$R_L = 47\Omega$ , $R_G = 10\Omega$ , $I_D = 200 \text{mA}$
Turn-Off Fall Time	tF	_	10.54	_		

Notes:8. Short duration pulse test used to minimize self-heating effect.9. Guaranteed by design. Not subject to product testing.

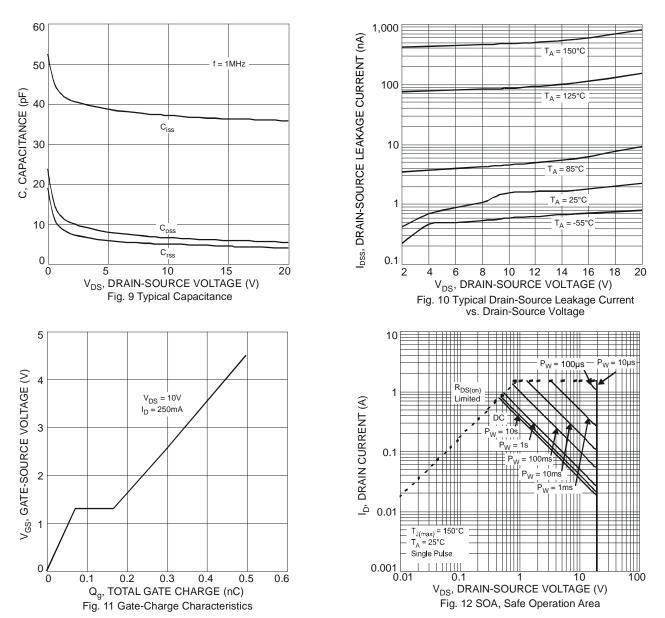










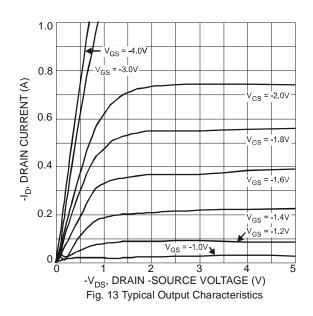


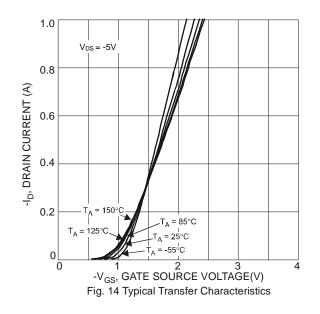


# Electrical Characteristics - Q2 P-CHANNEL (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)			- 76			
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	—	—	V	$V_{GS} = 0V, I_{D} = -1mA$
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	_	—	-100	nA	$V_{DS} = -20V, V_{GS} = 0V$
Cata Sauraa Laakaga			—	±1.0	^	$V_{GS} = \pm 5V, V_{DS} = 0V$
Gate-Source Leakage	Igss		—	±5.0	μΑ	$V_{GS} = \pm 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						·
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-0.5	—	-1.0	V	$V_{DS} = V_{GS}, I_D = -250 \mu A$
		_	0.67	0.97		$V_{GS} = -5V, I_{D} = -100 \text{mA}$
		—	0.7	1.0		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -100mA
Static Drain-Source On-Resistance	D	_	0.9	1.5	Ω	$V_{GS} = -2.5V, I_D = -80mA$
Static Drain-Source On-Resistance	RDS(ON)	_	1.2	2.0		Vgs = -1.8V, ID = -40mA
		_	1.5	3.0		Vgs = -1.5V, ID = -30mA
		_	5	—		Vgs = -1.2V, ID = -1mA
Forward Transfer Admittance	Y <sub>fs</sub>	_	0.7	_	S	V <sub>DS</sub> = -3V, I <sub>D</sub> = -100mA
Diode Forward Voltage	V <sub>SD</sub>	_	-0.75	-1.2	V	$V_{GS} = 0V, I_{S} = -330mA$
DYNAMIC CHARACTERISTICS (Note 9)						·
Input Capacitance	Ciss	—	46.1	-		
Output Capacitance	Coss	_	7.2	—	pF	$V_{DS} = -10V$ , $V_{GS} = 0V$ , f = 1.0MHz
Reverse Transfer Capacitance	Crss	—	4.9	-		
Gate Resistance	Rg	_	14.3	—	Ω	$V_{DS} = 0V, V_{GS} = 0V$
Total Gate Charge (V <sub>GS</sub> = -4.5V)	Qg	_	0.5	—		
Total Gate Charge (V <sub>GS</sub> = -10V)	Qg	_	0.85	_		$V_{DS} = -10V, I_{D} = -250mA$
Gate-Source Charge	Q <sub>gs</sub>	_	0.09	—	nC	
Gate-Drain Charge	Q <sub>gd</sub>		0.09	_	1	
Turn-On Delay Time	t <sub>D(ON)</sub>	_	8.5	_		
Turn-On Rise Time	tR	_	4.3	_		$V_{DD} = -3V, V_{GS} = -2.5V,$
Turn-Off Delay Time	tD(OFF)	_	20.2	_	ns	$R_{L} = 300\Omega,  R_{G} = 25\Omega,$
Turn-Off Fall Time	tF	_	19.2	_	1	I <sub>D</sub> = -100mA

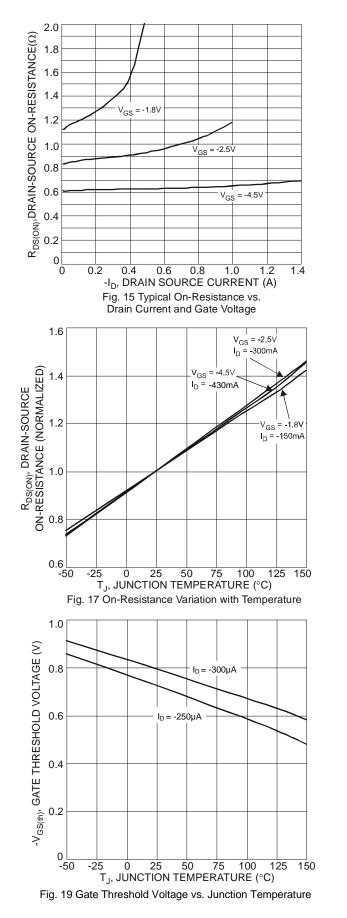
8. Short duration pulse test used to minimize self-heating effect.9. Guaranteed by design. Not subject to product testing. Notes:

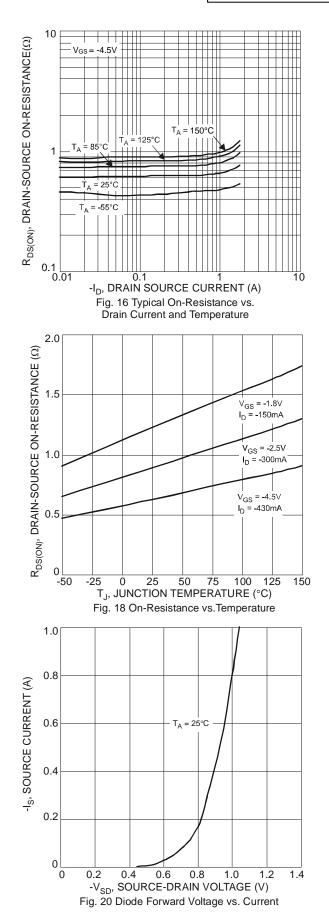






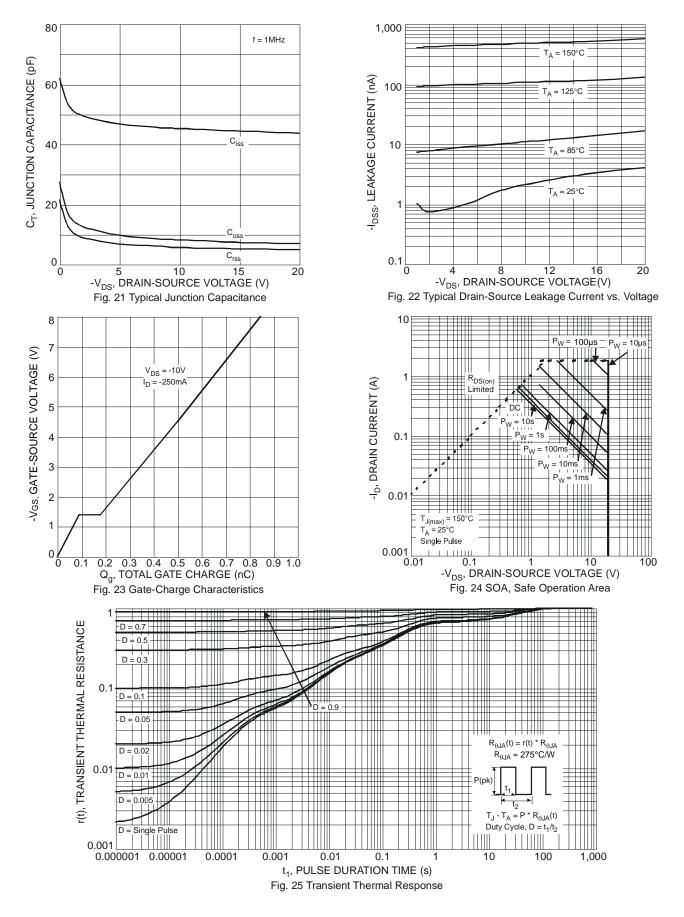
# DMC2400UV







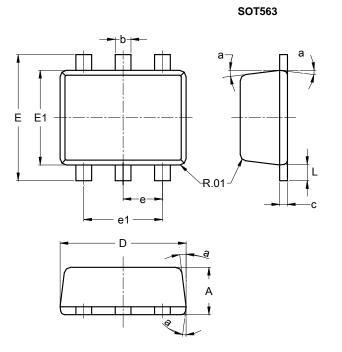
# **DMC2400UV**





#### **Package Outline Dimensions**

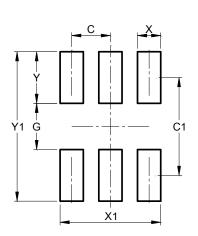
Please see http://www.diodes.com/package-outlines.html for the latest version.



	SO	T563	
Dim	Min	Max	Тур
Α	0.55	0.60	0.60
b	0.15	0.30	0.20
C	0.10	0.18	0.11
D	1.50	1.70	1.60
Е	1.55	1.70	1.60
E1	1.10	1.25	1.20
е			0.50
e1	0.90	1.10	1.00
L	0.10	0.30	0.20
а	8°	9°	7°
All	Dimens	sions in	mm

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	0.500
C1	1.270
G	0.600
Х	0.300
X1	1.300
Y	0.670
Y1	1.940

SOT563



#### IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

#### LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
  - 1. are intended to implant into the body, or
  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2020, Diodes Incorporated

www.diodes.com

# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by Diodes Incorporated manufacturer:

Other Similar products are found below :

614233C 648584F IRFD120 JANTX2N5237 FCA20N60\_F109 FDZ595PZ 2SK2545(Q,T) 405094E 423220D TPCC8103,L1Q(CM MIC4420CM-TR VN1206L 614234A 715780A NTNS3166NZT5G SSM6J414TU,LF(T 751625C IPP110N20N3GXK BUK954R8-60E NTE6400 SQJ402EP-T1-GE3 2SK2614(TE16L1,Q) DMN1017UCP3-7 EFC2J004NUZTDG ECH8691-TL-W FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE221 NTE222 NTE2384 NTE2941 NTE2945 NTE2946 NTE2960 NTE2969 NTE2976 NTE6400A NTE2916 NTE2956 NTE2911 DMN2080UCB4-7 TK10A80W,S4X(S STF35N65DM2 STW70N60DM6-4 SSM6P54TU,LF SSM6P69NU,LF DMP22D4UF0-7B DMN1006UCA6-7 DMN16M9UCA6-7